Apparatus and process for precise encapsulation interconnects Inventor: Rajendra Pendse e chip

U.S. Application No.: 10/081,425



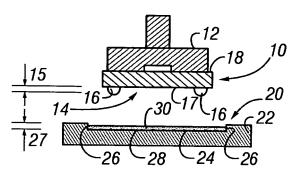
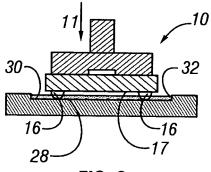


FIG. 1

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FIG. 2

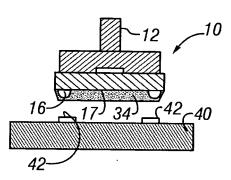


FIG. 3

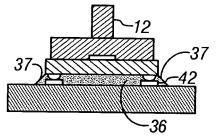


FIG. 4

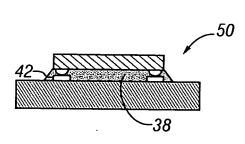


FIG. 5